



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220.
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED)

DIODES
INCORPORATED

PERICOM A PRODUCT LINE OF DIODES INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 12/06/16

DESCRIPTION: 32-Contact, Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZH (ZH32)

DOCUMENT CONTROL #: PD-2070

REVISION: C